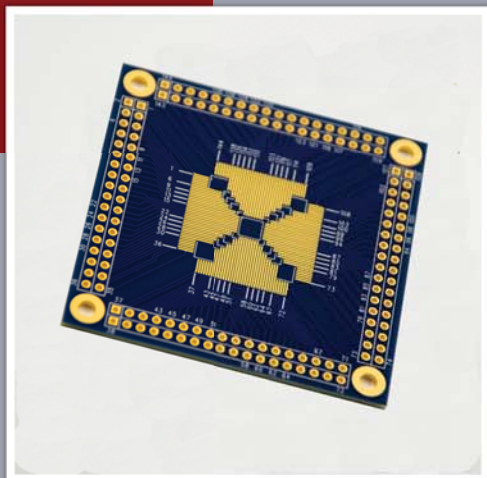


QFP/TQFP/PQFP Prototyping board

PT-QFP



SMT Pads:
32-144 Pins
0.5 / 0.8mm pitch

Hole Diameter:
0.047" (1.2mm)
plated holes

Hole Spacing:
0.1" (2.54mm)

T/H Pad:
0.08" (2.032mm)
round pad

Type/Finish:
FR-4 with
Electroless Nickel
Immersion Gold
(ENIG)

PCB Thickness:
0.062" (1.57mm)

Mounting Holes:
4-40 size, plated

Form Factor:
2.42" x 2.42"
(61.47 x 61.47mm)

The QFP prototyping boards are designed to allow quick and easy circuit prototyping of chips using the QFP, TQFP, or PQFP Packages. Two boards are available which allow parts with 0.5mm pitch or 0.8mm pitch to be soldered. The boards also offer 0.08" round pads with 0.047" plated holes spaced 0.1" apart which can be used to solder DIP headers or wires to interface with the chip. The spacing of the holes also allows the boards to be connected to a standard 0.1" pitch bread-board with ease.

Ordering Information

Part Number	No. of Pins	Pin Pitch
PT-QFP-32_144-0.5	32 - 144	0.5mm
PT-QFP-32_128-0.8	32 - 128	0.8mm